

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT4202213

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHANG-SHU KUO	12/13/2016
IN-GANN CHEN	12/14/2016
HUNG-TAO CHEN	12/14/2016
HAN-HSUAN CHENG	12/13/2016
RECEIVING PARTY DATA	
Name:	NATIONAL CHENG KUNG UNIVERSITY
Street Address:	NO.1, DAXUE RD., EAST DIST.,
City:	TAINAN CITY
State/Country:	TAIWAN
Postal Code:	701
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15391839
CORRESPONDENCE DATA	
Fax Number:	(626)571-9813
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	626-571-9812
Email:	RAYMONDC@DAVIDANDRAYMOND.COM
Correspondent Name:	DAVID AND RAYMOND PATENT FIRM
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Address Line 4:	MONTEREY PARK, CALIFORNIA 91754
ATTORNEY DOCKET NUMBER:	GDIP00415-USP
NAME OF SUBMITTER:	MICHAEL LEE
SIGNATURE:	/Michael Lee/
DATE SIGNED:	12/28/2016
Total Attachments: 4	
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UTILITY PATENT

Attorney's

Docket No.: 70DP00415-1JP

ASSIGNMENT

WHEREAS, I (we), Chang-Shu Kuo
whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented a
certain new and useful improvements in
Method of Fabricating Conductive Thin Film

(hereinafter referred to as the INVENTION) for which an application for United States Letters Patent was

☒ executed on even data herewith
☐ executed on:
☐ filed on:

Serial No.:

WHEREAS, NATIONAL CHENG KUNG UNIVERSITY
whose post office address is No. 1, Daxue Rd., East Dist., Tainan City 701, Taiwan (R.O.C.)
hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the
same in the United States;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby
acknowledged, I (we), ASSIGNOR, by these presents do sell, assign and transfer unto said ASSIGNEE, the
entire right, title, and interest in and to said INVENTION and application throughout the United States of
America, including any and all Letters Patent granted on any division, continuation, continuation-in-part
and reissue of said application.

ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in
connection with the filing, prosecution and maintenance of said application or any other patent
application(s) in the United States for said INVENTION, including additional documents that may be
required to affirm the rights of ASSIGNEE in and to said INVENTION, all without further consideration.
ASSIGNOR also agrees, without further consideration and at ASSIGNEE'S expense, to identify and
communicate to ASSIGNEE at ASSIGNEE'S request documents and information concerning the INVENTION
that are within ASSIGNOR'S possession or control, and to provide further assurances and testimony on
behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance
and defense of any patent application or patent encompassed within the terms of this instrument.
ASSIGNOR'S obligations under this instrument shall extend to ASSIGNOR'S heirs, executors, administrators
and other legal representatives.

ALSO, ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to
issue any and all Letters Patent referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title
and interest in and to the same, for ASSIGNEE'S sole use and behoof; and for the use and behoof of
ASSIGNEE'S legal representatives and successors, to the full end of the term for which such Letters Patent
may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment
and sale not been made.

ASSIGNOR authorizes Raymond Y. Chan to insert or complete any information in this document
needed to effect its recordal in the U.S. Patent and Trademark Office.

ASSIGNOR NAME: Chang-Shu Kuo

ADDRESS: Department of Materials Science and Engineering, National Cheng Kung University, 1 University Rd.,
Tainan 701, Taiwan R.O.C.

Chang-Shu Kuo
SIGNATURE

Dec 13, 2016
DATE

UTILITY PATENT

Attorney's

Docket No.: GDI000415-USP

ASSIGNMENT

WHEREAS, I (we), In-Gann Chen
whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented a
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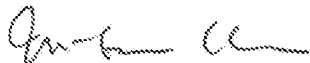
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ASSIGNOR NAME: In-Gann Chen

ADDRESS: Department of Materials Science and Engineering, National Cheng Kung University, 1 University Rd.,
Tainan 701, Taiwan R.O.C

SIGNATURE

Dec. 14, 2016

DATE

ASSIGNMENT

WHEREAS, I (we), Hung-Tao Chen
whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented a
certain new and useful improvements in
Method of Fabricating Conductive Thin Film
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ASSIGNOR NAME: Hung-Tao Chen

ADDRESS: Department of Materials Science and Engineering, National Cheng Kung University, 1 University Rd.,
Tainan 701, Taiwan R.O.C.

SIGNATURE

Hung-Tao Chen

DATE

Dec. 14, 2016

ASSIGNMENT

WHEREAS, I (we), Han-Hsuan Cheng
whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented a
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ASSIGNOR NAME: Han-Hsuan Cheng

ADDRESS: Department of Materials Science and Engineering, National Cheng Kung University, 1 University Rd.,
Tainan 701, Taiwan R.O.C.

Han-Hsuan Cheng
SIGNATURE

Dec 13, 2016
DATE